

# **DATA SHEET**

# **ANTI-SULFURATED CHIP RESISTORS**

AF series 5%, 1%

sizes 0201/0402/0603/0805/1206/1210/1218/2010/2512

RoHS compliant & Halogen free



YAGEO Phi(comp



# YAGEO Phicomp

#### SCOPE

This specification describes AF0201 to AF2512 chip resistors with anti-sulfuration capabilities.

#### <u>APPLICATIONS</u>

- Industrial Equipment
- Power Application
- Networking Application
- High-end Computer & Multimedia Electronics in high sulfur environment

# **FEATURES**

- Superior resistance against sulfur containing atmosphere
- Halogen free product and production
- · RoHS compliant
  - Products with lead free terminations meet RoHS requirements
  - Pb-glass contained in electrodes, resistor element and glass are exempted by RoHS
- Reduces environmentally hazardous waste
- High component and equipment reliability
- · Saving of PCB space
- Moisture sensitivity level: MSL I

#### ORDERING INFORMATION - GLOBAL PART NUMBER

0201 to 2512

Part number is identified by the series name, size, tolerance, packaging type, temperature coefficient, taping reel and resistance value.

#### **GLOBAL PART NUMBER**

# AF XXXX X X X X XX XXXX L

(1) (2) (3) (4) (5) (6) (7

# (I) SIZE

0201/0402/0603/0805/1206/1210/1218/2010/2512

# (2) TOLERANCE

 $F = \pm 1\%$  $| = \pm 5\%$ 

# (3) PACKAGING TYPE

R = Paper taping reel

K = Embossed plastic tape reel

#### (4) TEMPERATURE COEFFICIENT OF RESISTANCE

- = Base on spec

#### (5) TAPING REEL

07 = 7 inch dia. Reel	10 = 10 inch dia. Reel
13 = 13 inch dia. Reel	7D = 7 inch Dia. Reel with double quantity

# (6) RESISTANCE VALUE

I  $\Omega$  to 22  $M\Omega$ 

There are  $2\sim4$  digits indicated the resistance value. Letter R/K/M is decimal point, no need to mention the last zero after R/K/M, e.g. I K2, not I K20.

Detailed resistance rules are displayed in the table of "Resistance rule of global part number".

### (7) DEFAULT CODE

Letter L is system default code for ordering only (Note)

number Resistance coding ru	ıle Example
XRXX (1 to 9.76 Ω)	IR = I Ω IR5 = I.5 Ω 9R76 = 9.76 Ω
$XXRX$ (10 to 97.6 $\Omega$ )	$10R = 10 \Omega$ $97R6 = 97.6 \Omega$
XXXR (100 to 976 Ω)	100R = 100 Ω
XKXX (1 to 9.76 KΩ)	1K = 1,000 Ω $9K76 = 9760 Ω$
XMXX (1 to 9.76 MΩ)	$IM = 1,000,000 \Omega$ $9M76 = 9,760,000 \Omega$

Resistance rule of global part

#### **ORDERING EXAMPLE**

The ordering code for an AF0402 chip resistor, value  $100 \text{ K}\Omega$  with  $\pm 1\%$  tolerance, supplied in 7-inch tape reel with 10Kpcs quantity is: AF0402FR-07100KL.

#### NOTE

- All our R-Chip products are RoHS compliant and Halogen free. "LFP" of the internal 2D reel label states "Lead-Free Process"
- On customized label, "LFP" or specific symbol can be printed



Chip Resistor Surface Mount | AF | SERIES | 0201 to 2512



#### AF0201 / AF0402



No marking

Fig. I

## AF0603 / AF0805 / AF1206 / AF1210 / AF2010 / AF2512



Value=10 KΩ

E-24 series: 3 digits,  $\pm 5\%$ ,  $\geq 10\Omega$ 

First two digits for significant figure and 3rd digit for number of zeros

AF0603

Fig. 4

Fig. 2



E-24 series: 3 digits, ±1%

One short bar under marking letter

Fig. 3 Value =  $24 \Omega$ 



Value =  $12.4 \text{ K}\Omega$ 

E-96 series: 3 digits, ±1%

First two digits for E-96 marking rule and 3rd letter for number of zeros

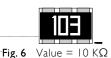
# AF0805 / AF1206 / AF1210 / AF2010 / AF2512



Both E-24 and E-96 series: 4 digits, ±1%

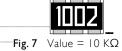
First three digits for significant figure and 4th digit for number of zeros

AF1218



E-24 series: 3 digits, ±5%

First two digits for significant figure and 3rd digit for number of zeros



Both E-24 and E-96 series: 4 digits, ±1%

First three digits for significant figure and 4th digit for number of zeros

# NOTE

For further marking information, please see special data sheet "Chip resistors marking". Marking of AF series is the same as RC series

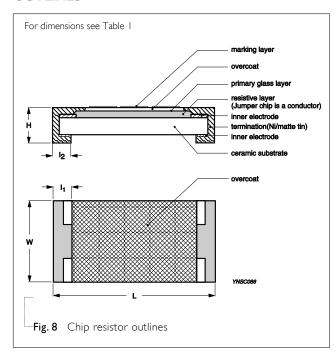
# CONSTRUCTION

The resistors are constructed on top of a high grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive glaze. The resistive glaze is covered by a lead-free glass. The composition of the glaze is adjusted to give the approximate required resistance value and laser trimming of this resistive glaze achieves the value within tolerance. The whole element is covered by a protective overcoat. Size 0603 and bigger is marked with the resistance value on top. Finally, the two external terminations (Ni / matte tin) are added. See fig.8

# **DIMENSIONS**

Table I	ble I For outlines see fig. 8				
TYPE	L (mm)	W (mm)	H (mm)	I <sub>I</sub> (mm)	l <sub>2</sub> (mm)
AF0201	0.60±0.03	0.30±0.03	0.23±0.03	0.10±0.05	0.15±0.05
AF0402	1.00 ±0.05	0.50 ±0.05	0.32 ±0.05	0.20 ±0.10	0.25 ±0.10
AF0603	1.60 ±0.10	0.80 ±0.10	0.45 ±0.10	0.25 ±0.15	0.25 ±0.15
AF0805	2.00 ±0.10	1.25 ±0.10	0.50 ±0.10	0.35 ±0.20	0.35 ±0.20
AF1206	3.10 ±0.10	1.60 ±0.10	0.55 ±0.10	0.45 ±0.20	0.40 ±0.20
AF1210	3.10±0.10	2,60±0.15	0.50±0.10	0.45±0.15	0.50±0.20
AF1218	3.10±0.10	4.60±0.10	0.55±0.10	0.45±0.20	0.40±0.20
AF2010	5.00±0.10	2,50±0.15	0.55±0.10	0.55±0.15	0.50±0.20
AF2512	6.35±0.10	3.10±0.15	0.55±0.10	0.60±0.20	0.50±0.20

#### **OUTLINES**



# **ELECTRICAL CHARACTERISTICS**

Table 2

Table	_					
	CHARACTERISTICS					
TYPE	RESISTANCE RANGE	Operating Temperature Range	Max. Working Voltage	Max. Overload Voltage	Dielectric Withstanding Voltage	Temperature Coefficient of Resistance
AF0201	$\pm$ 5% (E24), I $\Omega$ to IOM $\Omega$ $\pm$ 1% (E24/E96), I $\Omega$ to IOM $\Omega$ Zero Ohm Jumper < 0.05 $\Omega$	-55°C to +125°C	25 V	50 V	50 V	$1\Omega \le R \le 10\Omega$ , $-100/+350$ ppm/°C $10\Omega < R \le 10M\Omega$ , $\pm 200$ ppm/°C
AF0402			50 V	100 V	100 V	
AF0603	$\pm$ 5% (E24), I $\Omega$ to 22 M $\Omega$	_	75 V	150 V	100 V	$I \Omega \le R \le I0 \Omega$ , $\pm 200 \text{ ppm/}^{\circ}$
AF0805	$^{-}\pm$ 1% (E24/E96), I $\Omega$ to 10 M $\Omega$ Zero Ohm Jumper < 0.05 $\Omega$	_	150 V	300 V	300 V	10 $\Omega$ < R $\leq$ 10 M $\Omega$ , $\pm$ 100 ppm/°C 10 M $\Omega$ < R $\leq$ 22 M $\Omega$ , $\pm$ 200 ppm/°C
AF1206	· · · ·	-	200 V	400 V	500 V	701 132 4102 22 1 132, ±200 pp.110 C
AF1210		–55 °C to +155 °C⁻	200 V	500 V	500 V	
AF1218	$\pm$ 1% (E24/E96), I <b>Ω</b> to 10M	_	200 V	500 V	500 V	I <b>Ω</b> ≤ R≤ I0 <b>Ω</b> , <b>±</b> 200 ppm/°C
AF2010			200 V	500 V	500 V	$10\Omega < R \le 10M\Omega$ , ±200 ppm/°C
AF2512	, ,	<del>-</del>	200V	500V	500V	





**Chip Resistor Surface Mount** 

SERIES

ΑF

0201 to 2512

# FOOTPRINT AND SOLDERING PROFILES

Phicomp

For recommended footprint and soldering profiles of AF-series is the same as RC-series. Please see the special data sheet "Chip resistors mounting".

## PACKING STYLE AND PACKAGING QUANTITY

**Table 3** Packing style and packaging quantity

PACKING STYLE	reel Dimension	AF0201	AF0402	AF0603/0805/ 1206	AF1210	AF1218/2010/ 2512
Paper taping reel (R)	7" (178 mm)	10,000/20,000	10,000/20,000	5,000	5,000	
	10" (254 mm)		20,000	10,000		
	13" (330 mm)	50,000	50,000	20,000	20,000	
Embossed taping reel (K)	7" (178 mm)					4,000

#### NOTE

1. For paper/embossed tape and reel specification/dimensions, please see the special data sheet "Chip resistors packing".

## **FUNCTIONAL DESCRIPTION**

## **OPERATING TEMPERATURE RANGE**

AF0201 Range: -55 °C to + 125 °C

AF0402 - AF2512 Range: -55 °C to + 155 °C

# **POWER RATING**

Each type rated power at 70 °C:

AF0201=1/20W (0.05W)

AF0402=1/16 W (0.0625W)

AF0603=1/10 W (0.1W)

AF0805=1/8 W (0.125W)

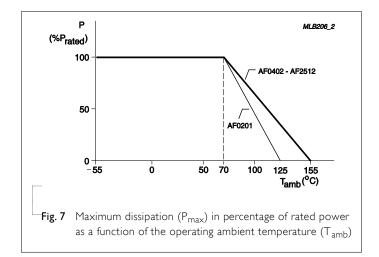
AFI206=I/4 W (0.25W)

AF1210=1/2W (0.5W)

AF1218=1W

AF2010=3/4W (0.75W)

AF2512=1W



#### **RATED VOLTAGE**

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

$$V = \sqrt{(P \times R)}$$

Where

V = Continuous rated DC or AC (rms) working voltage (V)

P = Rated power (W)

 $R = Resistance value (\Omega)$ 

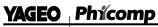


# Chip Resistor Surface Mount AF SERIES 0201 to 2512

# TESTS AND REQUIREMENTS

**Table 4** Test condition, procedure and requirements

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Temperature	IEC 60115-1 4.8	At +25/–55 °C and +25/+125 °C	Refer to table 2
Coefficient of Resistance		Formula:	
(T.C.R.)		T.C.R= $\frac{R_2-R_1}{R_1(t_2-t_1)} \times 10^6 \text{ (ppm/°C)}$	
		$R_1(t_2-t_1)$	
		Where	
		$t_1$ =+25 °C or specified room temperature $t_2$ =-55 °C or +125 °C test temperature	
		R <sub>1</sub> =resistance at reference temperature in ohms	
		R <sub>2</sub> =resistance at test temperature in ohms	
Life/Endurance	IEC 60115-1 4.25	At 70±2 °C for 1,000 hours, RCWV applied for	±(1.0%+0.05 Ω)
	MIL-STD-202 Method 108	1.5 hours on, 0.5 hour off, still air required	<100 m $\Omega$ for Jumper
High	MIL-STD-202 Method 108	1,000 hours at 155±5 °C, unpowered	$\pm$ (1.0%+0.05 $\Omega$ ) for 1% tol.
Temperature Exposure/			$\pm ($ 1.0%+0.05 $\Omega)$ for 5% tol.
Endurance at			$<$ 100 m $\Omega$ for Jumper
Upper Category			
Temperature			
Moisture	MIL-STD-202 Method 106	Each temperature / humidity cycle is defined at 8	$\pm (0.5\% \pm 0.05~\Omega)$ for 1% tol.
Resistance		hours, 3 cycles / 24 hours for IOd. with 25 °C /	$\pm ($ 1.0%+0.05 $\Omega)$ for 5% tol.
		65 °C 95% R.H, without steps 7a & 7b, unpowered	$<$ 100 m $\Omega$ for Jumper
		Parts mounted on test-boards, without	
		condensation on parts	
Thermal Shock	MIL-STD-202 Method 107	–55 / +125 °C	$\pm (0.5\% \pm 0.05 \ \Omega)$ for 1% tol.
		Number of cycles required is 300. Devices unmounted	$\pm (1\% + 0.05 \ \Omega)$ for 5% tol. <100 m $\Omega$ for Jumper
		Maximum transfer time is 20 seconds. Dwell time	1700 maz for jumper
		is 15 minutes	
Short Time	IEC60115-1 4.13	2.5 times of rated voltage or maximum overload	±(1.0%+0.05 Ω)
Overload		voltage whichever is less for 5 seconds at room	No visible damage
		temperature	
Bending	IEC 60115-1 4.33	Chips mounted on a 90 mm glass epoxy resin	±(1.0%+0.05 Ω)
	IEC 60068-2-21	PCB (FR4)	$<$ 100 m $\Omega$ for Jumper
		Bending: 0201/0402: 5 mm 0603/0805: 3 mm 1206 & above: 2 mm	No visible damage
		Bending time: 60±5 seconds	



# Chip Resistor Surface Mount AF SERIES 0201 to 2512

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Biased Humidity (steady state)	IEC 60115-1 4.37	Steady state for 1,000 hours at 40°C / 95% R.H. RCWV applied for 1.5 hours on and 0.5 hour off	±(3.0%+0.05 Ω)
Solderability			
- Resistance to Soldering Heat	IEC 60115-1 4.18 MIL-STD-202 Method 215	Condition B, no pre-heat of samples Lead-free solder, 260±5 °C, 10±1 seconds immersion time Procedure 2 for SMD: devices fluxed and cleaned with isopropanol	$\pm (0.5\% + 0.05~\Omega)$ for 1% tol. $\pm (1.0\% + 0.05~\Omega)$ for 5% tol. <50 m $\Omega$ for Jumper No visible damage
- Wetting	J-STD-002	Electrical test not required Magnification 10X SMD conditions:  (a) Method B, aging 4 hours at 155 °C dry heat, lead-free solder bath at 245 °C  (b) Method B, dipping at 215 °C for 3 seconds	Well tinned (≥95% covered) No visible damage
FOS	ASTM-B-809-95	Sulfur (saturated vapor) 1,000 hours, 60±2 °C, 91-93% R.H., unpowered	±(1.0%+0.05 Ω)



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# **REVISION HISTORY**

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version I	Sep. 27, 2013	-	- Size 0201/1210/1218/2010/2512 extend
Version 0	Jan 07, 2011	-	- First issue of this specification

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